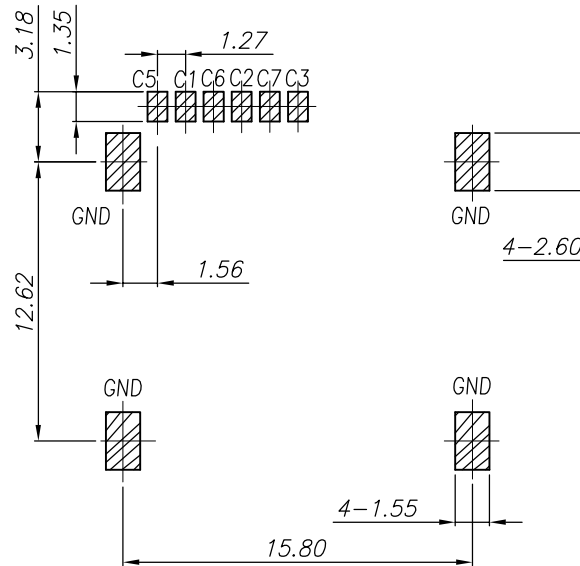
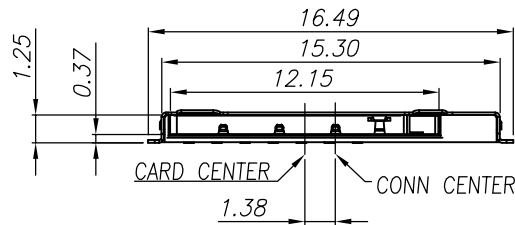
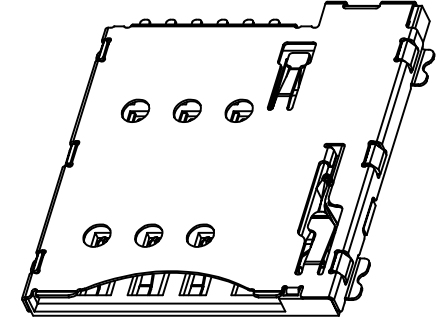
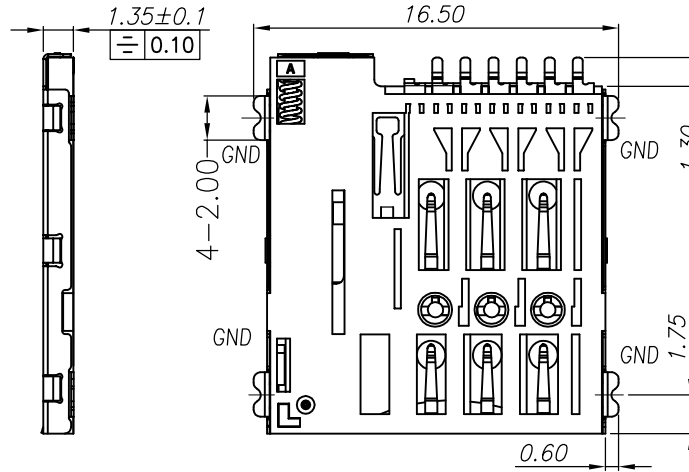
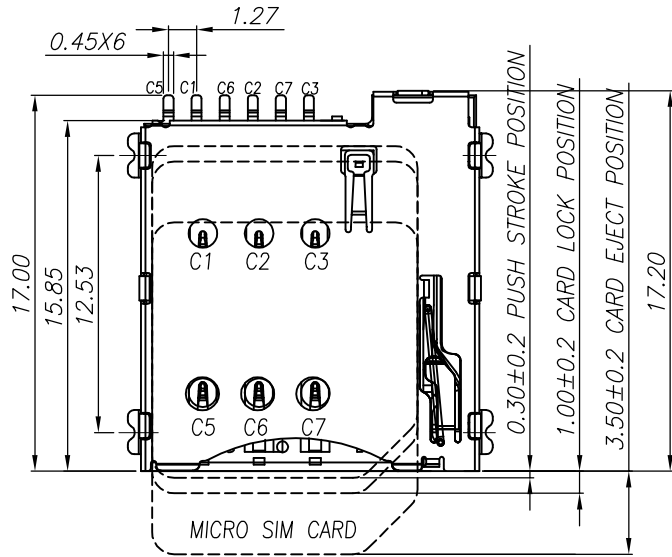
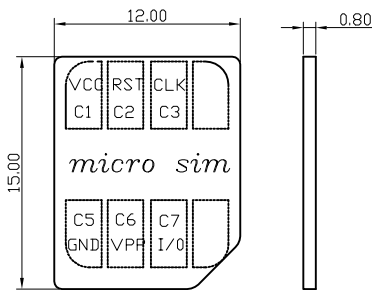


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2012/10/29



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP



MICRO SIM CARD

■ CIRCUIT TRACE KEEP OUT AREA
 ▨ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

NOTES:

MATERIAL:

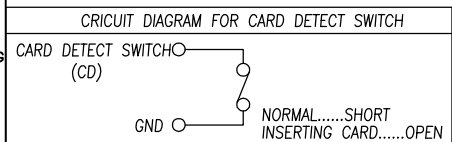
Insulator: High Temperature Thermoplastic,UL 94V-0.
 Contact: Copper Alloy
 Shell: STAINLESS

PLATING:

Contact: Plated 30u'' Ni Overall Contact Au 1U
 Shell: Plated 30u'' Ni Overall
 Plated 1u''Au Selective Contact Area

Electrical:

Current Rating :0.5mA AC/DC max.
 Voltage Rating :125V AC/DC
 Ambient Temperature Range :-20° C~+60° C
 Storage Temperature Range :-40° C~+70° C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩmax.
 Insulation Resistance:1000MΩmin./500VDC
 Mating Cycles:5,000 Insertions
 Temperature: 260° C ±5°



GENERAL TOLERANCE		DWG NO.	JYSA0529-001	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5°	Title	1.35H 6PIN PUSH MICRO SIM CARD CONNECIOR	CHKD:		UNIT	mm
.X±0.35	.x'±2°			DR:			
.XX±0.25	.xx'±1°	Part NO.	JYS-SIM135-054	Date	2012/10/29		
.XXX±0.15	.xxx'±0.5°						
SHEET	1/1			JYSCONN Shenzhen JYSCONN Electronics Co., LTD.			

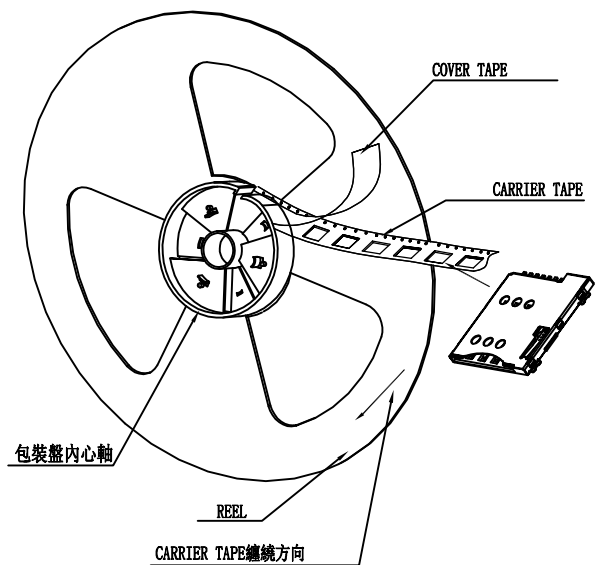
包装作业规范

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2012/10/29

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

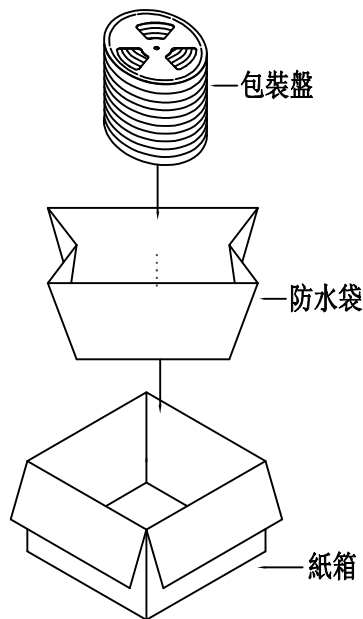
一.

- 1) 将成品一一放入包装盘内, 依同一方向放入.
- 2) 包装时, 如图所示.
- 3) 一个包装盘放置1000个成品.



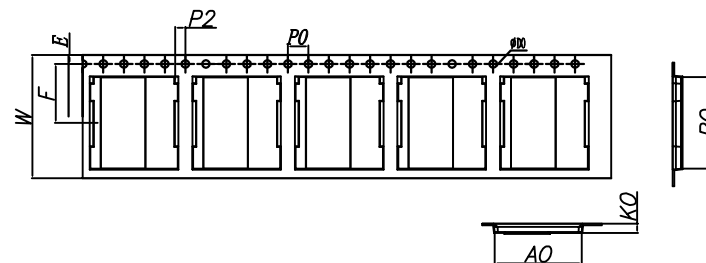
二.

- 1) 一只纸箱可放置5个包装盘.
- 2) 一只纸箱可放5000PCS的成品.
- 3) 将成品放入包装盘内包装完后再装箱.



三.

- 1) RELI载带尺寸图.



ITEM	W	AO	BO	KO	P	F	E	SO	DO	PO	P2
DIM	24.00±0.10	17.0±0.10	17.85±0.10	2.0±0.10	20.0±0.10	1.50±0.10	1.75±0.10	0.00±0.10	1.50±0.10	4.00±0.10	2.00
ALTERNATE											

产品单重: 0.6 g
 每盘单重: 800 g
 每箱单重: 4100 g (5000 PCS)

GENERAL TOLERANCE		DWG NO.	JYSA0529-001	APPD:	WIND	Scale	1:1
X.±0.45	.x'±5°	Title	1.35H 6PIN PUSH MICRO SIM CARD CONNECIOR	CHKD:		UNIT	mm
.X±0.35	.x'±2°			DR:			
.XX±0.25	.xx'±1°	Part NO.	包装图	Date	2012/10/29		
.XXX±0.15	.xxx'±0.5°						
SHEET	1/1			Shenzhen JYSCONN Electronics Co., LTD.			